

# HiPerFET™ Power MOSFETs

## IXFX 120N20 IXFK 120N20

 $V_{DSS} = 200 \text{ V}$   $I_{D25} = 120 \text{ A}$   $R_{DS(on)} = 17 \text{ m}\Omega$ 

t<sub>..</sub> ≤ 250 ns

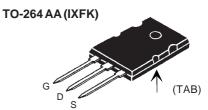
PLUS 247™ (IXFX)

## Single MOSFET Die

Preliminary data sheet

Symbol	mbol Test Conditions Maxim		
V <sub>DSS</sub> V <sub>DGR</sub>	$T_J = 25^{\circ}\text{C}$ to 150°C $T_J = 25^{\circ}\text{C}$ to 150°C; $R_{GS} = 1 \text{ M}\Omega$	200 200	V V
V <sub>GS</sub> V <sub>GSM</sub>	Continuous Transient	±20 ±30	V V
D25 D104 DM AR	$T_{\rm C} = 25^{\circ}{\rm C}$ (MOSFET chip capability) $T_{\rm C} = 104^{\circ}{\rm C}$ (External lead capability) $T_{\rm C} = 25^{\circ}{\rm C}$ , pulse width limited by $T_{\rm JM}$ $T_{\rm C} = 25^{\circ}{\rm C}$	120 76 480 120	A A A
E <sub>AR</sub> E <sub>AS</sub>	$T_{c} = 25^{\circ}C$ $T_{c} = 25^{\circ}C$	64 3	mJ J
dv/dt	$I_{_{S}} \leq I_{_{DM}}$ , di/dt $\leq$ 100 A/ $\mu$ s, $V_{_{DD}} \leq V_{_{DSS}}$ $T_{_{J}} \leq$ 150°C, $R_{_{G}} =$ 2 $\Omega$	15	V/ns
$\overline{P_{D}}$	T <sub>C</sub> = 25°C	560	W
T <sub>J</sub>		-55 +150	°C
T <sub>JM</sub> T <sub>stg</sub>		150 -55 +150	°C °C
T <sub>L</sub>	1.6 mm (0.063 in.) from case for 10 s	300	°C
M <sub>d</sub>	Mounting torque TO-264	0.9/6	Nm/b.in.
Weight	PLUS 247 TO-264		6 g 10 g

# (TAB)



G = Gate	D = Drain
S = Source	TAB = Drain

#### **Features**

- International standard packages
- $\bullet \ \, \mathsf{Low} \,\, \mathsf{R}_{\mathsf{DS}\, \mathsf{(on)}} \,\, \mathsf{HDMOS^{\mathsf{TM}}} \,\, \mathsf{process}$
- Rugged polysilicon gate cell structure
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
  - easy to drive and to protect
- Fast intrinsic rectifier

Symbol	<b>Test Conditions</b>	$(T_J = 25^{\circ}C, \text{ unless})$	Characteristic Values (T <sub>J</sub> = 25°C, unless otherwise specified) min.   typ.   max.		
V <sub>DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = 3\text{mA}$	200		V	
V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 8mA$	2.0		4.0 V	
I <sub>GSS</sub>	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0$			±200 nA	
I <sub>DSS</sub>	$V_{DS} = V_{DSS}$ $V_{DS} = 0 V$	T <sub>J</sub> = 25°C T <sub>.</sub> = 125°C		100 μA 2 mA	

#### **Applications**

- · DC-DC converters
- Battery chargers
- Switched-mode and resonant-mode power supplies
- · DC choppers
- AC motor control
- Temperature and lighting controls

#### Advantages

 $17~\text{m}\Omega$ 

- PLUS 247<sup>™</sup> package for clip or spring mounting
- · Space savings
- High power density

IXYS reserves the right to change limits, test conditions, and dimensions.

 $V_{GS} = 10 \text{ V}, I_{D} = 0.5 \cdot I_{D25}$ 

 $R_{\scriptscriptstyle DS(on)}$ 



Symbol	Test Conditions	$(T_J = 25^{\circ}C, \text{ unless of } min.)$		stic Values se specified) max.
g <sub>fs</sub>	$V_{DS} = 10 \text{ V}; I_{D} = 0.5 \cdot I_{D25}$	Note 1 40	77	S
C <sub>iss</sub>	)		9100	pF
C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f =$	1 MHz	2200	pF
$\mathbf{C}_{rss}$	J		1000	pF
t <sub>d(on)</sub>	)		40	ns
t <sub>r</sub>	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DS}$	$I_{DSS}$ , $I_{D} = 0.5 \bullet I_{D25}$	65	ns
t <sub>d(off)</sub>	$R_{\rm G} = 1 \Omega$ (External),		110	ns
t,			35	ns
Q <sub>g(on)</sub>	)		300	nC
$\mathbf{Q}_{gs}$	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DS}$	$I_{DSS}$ , $I_{D} = 0.5 \bullet I_{D25}$	50	nC
$\mathbf{Q}_{gd}$	J		170	nC
R <sub>thJC</sub>				0.22 K/W
R <sub>thCK</sub>			0.15	K/W

#### Source-Drain Diode

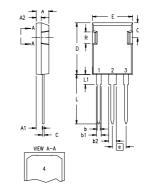
**Characteristic Values** 

		$(T_J = 25^{\circ}C, \text{ unless otherwise specifity})$			
Symbol	Test Conditions	min.	typ.	max.	
	\/ O\/			400	,

I <sub>s</sub>	V <sub>GS</sub> = 0 V		120	Α
I <sub>SM</sub>	Repetitive; pulse width limited by T <sub>JM</sub>		480	Α
V <sub>SD</sub>	$I_F = I_S$ , $V_{GS} = 0$ V, Note 1		1.5	V
t <sub>rr</sub>	)		250	ns
$\mathbf{Q}_{RM}$	$I_F = 50A, -di/dt = 100 A/\mu s, V_R = 100 V$	0.8		μС
I <sub>RM</sub>	J	8		Α

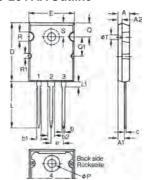
Note: 1. Pulse test,  $t \le 300~\mu s$ , duty cycle  $d \le 2~\%$ 

## PLUS247™ (IXFX) Outline



Dim.	Millimeter		Inc	hes
	Min.	Max.	Min.	Max.
Α	4.83	5.21	.190	.205
A,	2.29	2.54	.090	.100
A <sub>2</sub>	1.91	2.16	.075	.085
b	1.14	1.40	.045	.055
b,	1.91	2.13	.075	.084
b <sub>2</sub>	2.92	3.12	.115	.123
С	0.61	0.80	.024	.031
D	20.80	21.34	.819	.840
E	15.75	16.13	.620	.635
е	5.45 BSC		.215	BSC
L	19.81	20.32	.780	.800
L1	3.81	4.32	.150	.170
Q	5.59	6.20	.220	.244
R	4.32	4.83	.170	.190

### **TO-264 AA Outline**



Dim.	Millimeter		Inches		
	Min.	Max.	Min.	Max.	
Α	4.82	5.13	.190	.202	
A1	2.54	2.89	.100	.114	
A2	2.00	2.10	.079	.083	
b	1.12	1.42	.044	.056	
b1	2.39	2.69	.094	.106	
b2	2.90	3.09	.114	.122	
С	0.53	0.83	.021	.033	
D	25.91	26.16	1.020	1.030	
Е	19.81	19.96	.780	.786	
е	5.46 BSC		.215 BSC		
J	0.00	0.25	.000	.010	
K	0.00	0.25	.000	.010	
L	20.32	20.83	.800	.820	
L1	2.29	2.59	.090	.102	
Р	3.17	3.66	.125	.144	
Q	6.07	6.27	.239	.247	
Q1	8.38	8.69	.330	.342	
R	3.81	4.32	.150	.170	
R1	1.78	2.29	.070	.090	
S	6.04	6.30	.238	.248	
Т	1.57	1.83	.062	.072	

Fig. 1. Output Characteristics at 25°C

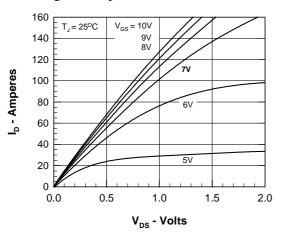


Fig. 3. R<sub>DS(ON)</sub> vs. Drain Current

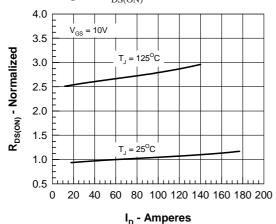


Fig. 5. Drain vs. Case Temperature

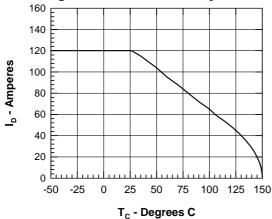


Fig. 2. Output Characteristics at 125°C

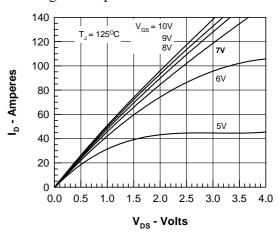


Fig. 4. R<sub>DS(ON)</sub> vs. T<sub>J</sub>

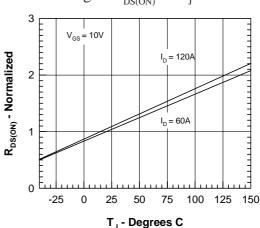


Fig. 6. Admittance Curves

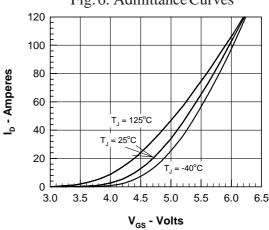




Fig. 7. Gate Charge Characteristic Curve

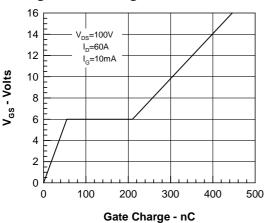


Fig. 8. Capacitance Curves 20000 Ciss 10000 Capacitance - pF 5000 f = 1 MHz Coss Crss 1000 500 35 25 5 10 15 20 V<sub>DS</sub> - Volts

Fig. 9. Source Current vs. Source to Drain Voltage

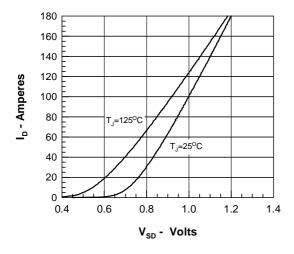
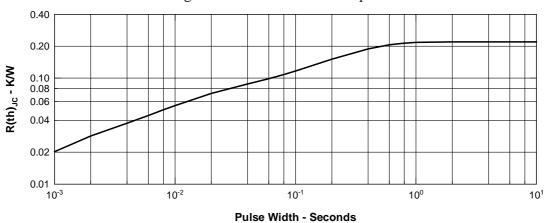


Fig. 10. Maximum Thermal Impedance



IXYS reserves the right to change limits, test conditions, and dimensions.

4,881,106

